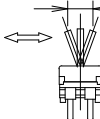
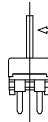
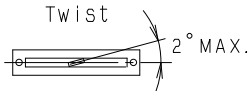
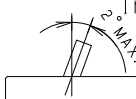
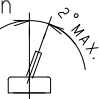
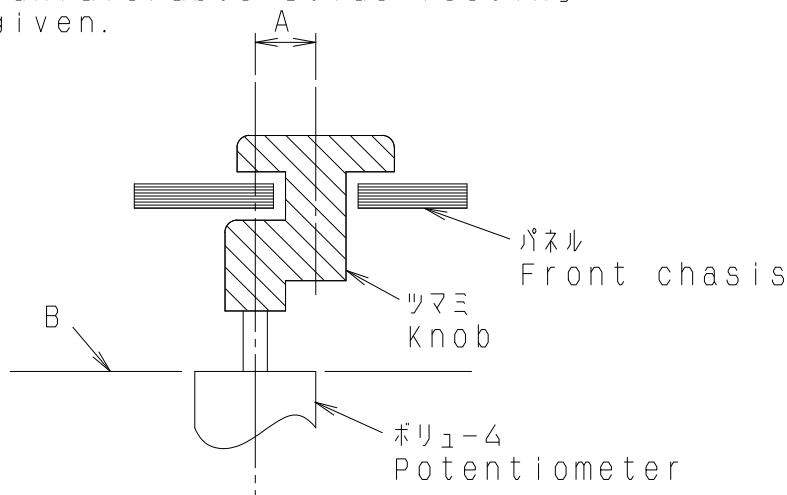


CLASS No.		TITLE	
		STANDARD TYPE POTENTIOMETER (SLIDE)	
ELECTRICAL			
1. Overall resistance : 10kΩ±20%			
2. Minimum resistance : Across term. 1-2 30Ω max. , Across term. 2-3 50Ω max.			
3. Taper : B Taper			
4. Rated power : 0.125Watts			
5. Rated voltage : Rated voltage = $\sqrt{P \cdot R}$ (V)			
P : rated power (W)			
R : nominal overall resistance (Ω)			
When the rated voltage exceeds the maximum operating voltage the maximum operating voltage shall be the rated voltage.			
Maximum operating voltage : A.C. 200 V , D.C. 10 V			
6. Dielectric test : Units shall be designed to withstand 300 volts A.C. 50 Hz R.M.S. between resistance elements and case for a period of one minute without damage or arcing.			
7. Insulation resistance : Greater than 100 megohms between resistance elements and case when tested by a 250 volts D.C. insulation resistance meter.			
8. Sliding life test : 15,000 cycles.			
9. Tracking error : 2dB at the point 50% travel.			
*Lever shall be operable with speed of 20 mm per sec. without noise by static electricity.			

CLASS NO.	TITLE			
	STANDARD TYPE POTENTIOMETER (SLIDE)			
MECHANICAL				
1.Travel : Specified in particular Figure.				
2.Operating force : 0.3N - 2.5N (Note 1)				
3.Starting force : Operating force + 1N max. (Note 1)				
(Note 1) Measuring temperature : 5℃ - 35℃				
Measuring point : 5 mm from lever end .				
Sliding speed : 20 mm per sec.				
4.Stop strength :				
50N at a position 5 mm from mounting surface.				
5.Lever lateral play :				
When an alternating bending moment of 25mN·m is applied perpendicular to the direction of lever travel , the both sides movement of the lever shall be less than 2(2xL/20)mm.				
L : Lever length on the measurement point from mtg. surface.				
(Note 2) Exempt warping of insulated lever.				
M = 25mN·m  Lever lateral play				
6.Lever strength :				
(1) To be resistant with 50N static force of pull or push applied to lever in thrust direction for 10 seconds without damage.				
(2) To be resistant with following static force applied to lever in vertical direction to lever driving for 10 seconds without damage.				
① No damage with an application of 0.2N·m : In case of pot., mounted to chassis with screws.				
② No damage with an application of 0.2N·m : in case of pot., mounted to P.C.B. with both terminals and mounting plate.				
50N  (1) 0.2N·m  (2)				
7.Lever inclination and twist :				
 Twist 2° MAX.  Inclination 2° MAX.  2° MAX.				
8.Resistance to soldering heat : 3 sec. max. at 350℃				
ALPSALPINE CO.,LTD.				
APPD. CHKD. DSGD. TITLE				
'96-04-01 '96-04-01 '96-04-01 SPECIFICATIONS				
Y.YOSHIOKA H. ITO H. KIMURA				
DOCUMENT NO.				
RS45112A0MEB14 (2/3)				

PRECAUTION IN USE

- The longer the length up to operating point, the more unfavorable slide feeling will be given. A



- There is a possibility that might be affected by contact resistance of resistive element and wiper in case of low impedance of output side in voltage regulation circuit. for this reason, we require that you adjust to impedance of output side more than 100 times of total resistance.

					ALPSALPINE CO., LTD.			
					APPD.	CHKD.	DSGD.	TITLE
					通・設計試作 '07-4- 5 池之上	通・設計試作 '07-4- 5 大矢	通・設計試作 '07-4. 5 玉田	スライド"ホ"リユーム 仕様書 SPECIFICATIONS
ORIGINAL	1991-07-03	Y・Y	K・N	S・A				DOCUMENT NO.
SYMB	DATE	APPD	CHKD	DSGD	450001-200			

RS45112A0MFB14

はんだ付け条件

FOLLOW THE NEXT CONDITIONS FOR SOLDERING

1. はんだ SOLDER

JIS Z 3282に規定のA30C5はんだを使用

A30C5 solder specified in JIS Z 3282.

2. 使用基板 BOARD IN USE

両面スルーホール基板又は、片面銅張積層板 板厚 $t=1.6\text{mm}$

Double-faces through-hole board or Single-face copper laid laminate board.

Plate thickness (t)= 1.6mm

3. 自動はんだ<DIP条件>

(1) レハ" - 位置 センター付近に設定願います。

(2) フラックス比重 0.83 ± 0.01 (発泡式)

(3) フラックス高さ フ" リント基板の板厚の半分の位置にフラックスの上面が接するレハ" ル (図1)
又、ホ" リューム挿入面への流れ込みのないこと。(フラックス上がり、飛散に注意)

(4) フ" リヒート温度 100°C max. 時間1分以内. (フ" リント基板のホ" リューム挿入側の温度)

(5) はんだ温度 260°C max. 時間5秒以内. はんだ回数は1回までとする。

IN THE CASE OF DIP SOLDERING

(1) State of potentiometer

Position a lever in the vicinity of center.

(2) Specific Gravity of Flux

0.83 ± 0.01 (foaming type)

(3) Height of Flux face

A level of the upper face of flux for reaching the position at a half of the plate thickness of printed board. (Fig. 1)

Further, no flow of flux invading on the surface of printed board on the side of installing potentiometer is allowed.

(4) Preheat condition

100°C max., within 1 minute

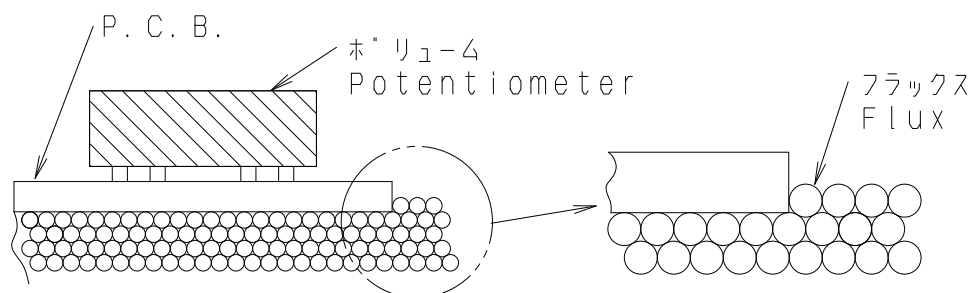
(Temperature on the side of installing printed board is designated.)

(5) Soldering condition

Solder temperature; 260°C max.

Soldering period ; within 5 seconds

Time of soldering ; only one time is permitted



(Fig. 1)

4. 手はんだ IN THE CASE OF MANUAL SOLDERING

はんだ温度 350°C max. 時間3秒以内 はんだ回数は1回までとする。

Solder temperature ; 350°C max.

Soldering period ; within 3 seconds

Time of soldering ; only one time is permitted

					ALPSALPINE CO., LTD.			
					APPD.	CHKD.	DSGD.	TITLE
					PD1-ENG1 '95.7.24 YOSIOKA	PD1-ENG1 '95.7.24 KIMURA	PD1-ENG1 '95.7.24 Y. SAITOH	スライト" ホ" リューム 仕様書 SPECIFICATIONS 1/2
ORIGINAL	'91-9-3	Y・Y	S・A	S・S	DOCUMENT NO.			
SYMB	DATE	APPD	CHKD	DSGD	450001-201			

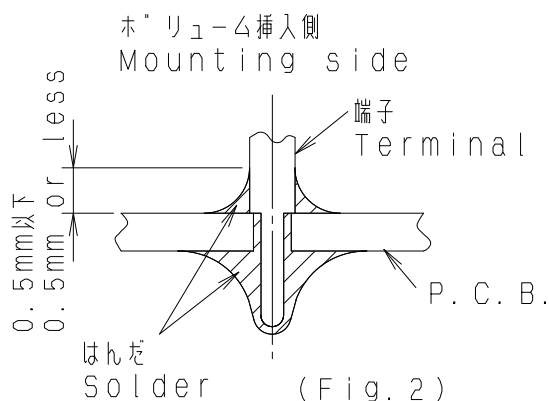
RS45112A0MEB14

5. 注意事項

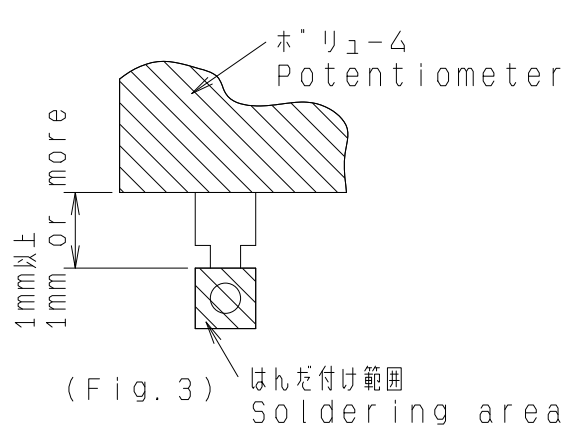
- (1) はんだ付けの際に、端子にストレスを加えないで下さい。例えば、端子に熱を加えたまま製品を動かしますと、かしめ力[※]及び電気的特性が劣化する恐れがあります。
- (2) 両面スルーホール基板を使用する場合は、ホ[※]リウム挿入側の端子取付穴に、はんだランド[※]がないようにご配慮願います。ホ[※]リウム挿入側での配線が必要な場合は端子取付穴からの直接取り出しを避けスルーホール配線用の穴を設けるなどのご配慮をお願いします。
- (3) ホ[※]リウム挿入側へのはんだ上がりは、はんだ熱による端子接触不良の発生原因となりますので(図2)を参照願います。
- (4) リート[※]配線の場合、ホ[※]リウム本体と、はんだ付け部の距離を1mm以上開けてはんだ付け願います。(図3)
- (5) はんだ付けによるホ[※]リウムへの影響は、フ[※]リント基板の大きさ、ホ[※]リウムの取付け位置、はんだ槽の大きさ、等により異なりますのであらかじめ実使用状態で実施し、異常のないことを確認の上、はんだ付けして下さい。

MATTERS TO BE NOTED

- (1) Do not add any stress on terminals in the case of soldering. For instance, forced movement of potentiometer with terminals being heated may probably deteriorate the electric features due to generation of looseness in connection between resistant board and terminals.
- (2) Avoid use of double-faces through-hole board as much as possible. If it is necessary to use it, Do not apply through-hole plating to a hole in which a potentiometer is inserted, and install a land to which terminals are soldered only on a face oppsite to the face on the side of installing potentiometer.
- (3) Use caution to soldering process so as to prevent solder from rising up to the surface of printed board on the side of installing potentiometer, because defective contact may take place in terminal connecting part due to soldering heat . (Fig.2)
- (4) In the case of lead wiring, solder it so that a gap of 1 mm or more may be reserved between the potentiometer body and soldering part. (Fig.3)
- (5) The grade of influence of soldering exerted on the potentiometer depends upon the size of a printed board, installing position of the potentiometer, and the size of a solder bath etc. Therefore, make sure, in advance, of no abnomal state under the conditions of soldering to be carried our at present.



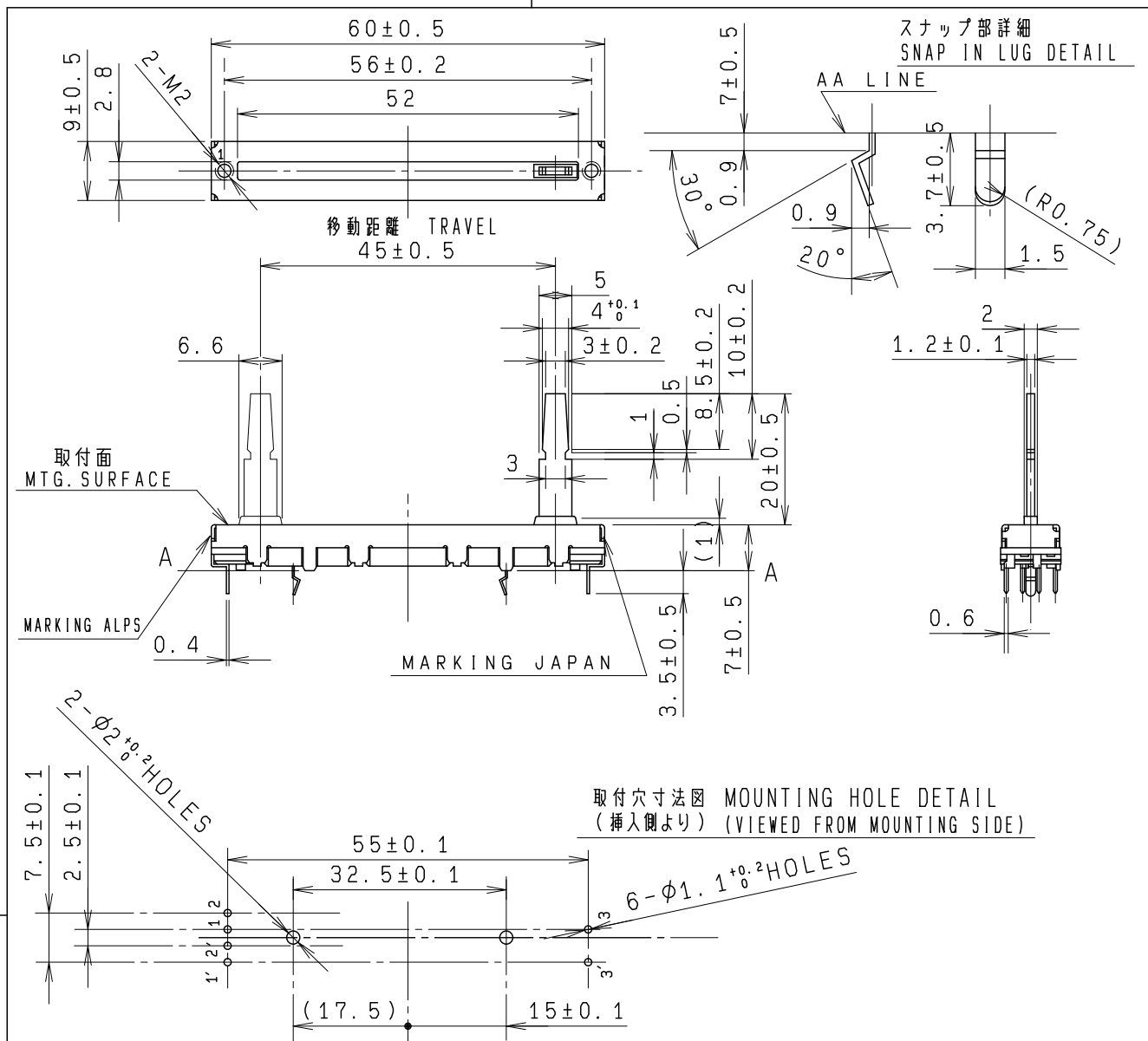
(Fig. 2)



(Fig. 3)

					ALPSALPINE CO.,LTD.			
					APPD.	CHKD.	DSGD.	TITLE
					PD1-ENG1 '95.7.24 YOSIOKA	PD1-ENG1 '95.7.24 KIMURA	PD1-ENG1 '95.7.24 Y.SAITOH	スライト [※] ホ [※] リウム 仕様書 SPECIFICATIONS 2/2
ORIGINAL	'91-9-3	Y・Y	S・A	S・S	DOCUMENT NO.			
SYMB	DATE	APPD	CHKD	DSGD	450001-201			

RS45112A0MEB14



- NOTES 1. MOUNTING SCREW THREAD LENGTH IS CHASSIS THICKNESS +2mmMAX.
取付用ネジの首下長さは、シャーシ板厚 +2mm以下とする。
2. TOP SIDE OF KNOB SHALL BE MOUNTED TO LEVER WITHIN 30mm LENGTH FROM LEVER MTG. SURFACE.
取付面からツマミ先端まで 30mm以内でご利用願います。
3. SNAP PORTION IS DESIGNED BASED ON 1.6mm THICK P.C.B.
スナップ部は、P.C.B. 板厚 1.6mm 基準にて設計してあります。

製品質量 5.7 g
WEIGHT

指定なき部分の許容差 TOLERANCES UNLESS OTHERWISE SPEC	
$L \leq 10$	± 0.3
$10 < L < 100$	± 0.5
$100 \leq L$	± 0.8
角度 ANGULAR DIMENSION	$\pm 5^\circ$

PART NO.		NAME			MATERIAL NAME / CODE			FINISH	
					ALPSALPINE CO.,LTD.				
					DSGD. セツケイ K, SATOU ' 93-06-16		SCALE 1 : 1	NO R545112A0420A S 4 5 2 8 P 4 0 8 A	
					CHKD. S, ABE ' 93-06-16			TITLE SLIDE POTENTIOMETER DUAL UNIT	
					APPD. Y, YOSHIOKA ' 93-06-16		UNIT mm	DOCUMENT NO. 4211	
SYMB	DATE	APPD	CHKD	DSGD					